

THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF VOLTSERVER. ANY REPRODUCTION AS A PART OR WHOLE WITHOUT THE WRITTEN PERMISSION OF VOLTSERVER IS PROHIBITED

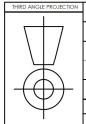
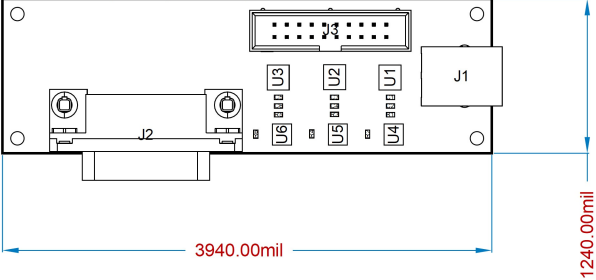
E												000000		REV		F				
REV STATUS		REV										REVISIONS								
OF SHEETS		SHEET										ZONE	REV	DESCRIPTION	DATE	APPROVED				

- NOTES:
- MATERIAL: FR4 180TG
 - INNER AND OUTER COPPER LAYERS: 1 OZ
 - 4 LAYERS, FINAL THICKNESS OF 0.062"
 - BLACK SOLDER MASK BOTH SIDES
 - WHITE SILKSCREEN TOP SIDE
 - ELECTROLESS NICKEL IMERSION GOLD (ENIG) FINISH
 - MINIMUM HOLE SIZE: 10 MIL
 - MINIMUM TRACE SPACING: 8 MIL

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
Top Solder		0.40mil	Solder Resist	Solder Mask	GTS
Copper	Top Layer	1.40mil		Signal	GTL
Core		10.00mil	FR-4	Dielectric	
Copper	GND Plane	1.40mil		Internal Plane	GP1
Prepreg		35.60mil		Dielectric	
Copper	3.3V Plane	1.40mil		Internal Plane	GP2
Core		10.00mil		Dielectric	
Copper	Bottom Layer	1.40mil		Signal	GBL
Surface Material	Bottom Solder	0.40mil	Solder Resist	Solder Mask	GBS
Bottom Overlay				Legend	GBO
Total thickness: 62.00mil					

View from Top side (Scale 1:1)



APPLICATION	USED ON	NEXT ASSY

PART NO:	APPROVALS	DATE
ENGINEER:		
DESIGNER:		
CHECKER:		
Reference Documents		
BOM DOC:		
ASSY DOC:		
SCN DOC:		
PCB DOC:		
DESIGN ITEM: =Project	DESIGN ITEM REVISION:	
TITLE: ETX8 PROGRAMMER		
SIZE: B	CAGE CODE:	DWG NO:
SCALE:	FILE NAME: dtb-218-AW1.PCBdWf	SHEET: 1 OF 1